# 2SC3553

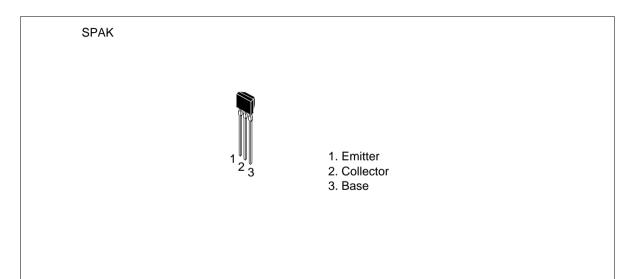
## Silicon NPN Epitaxial

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#### Application

Low frequency amplifier

#### Outline





#### 2SC3553

#### **Absolute Maximum Ratings** ( $Ta = 25^{\circ}C$ )

Item	Symbol	Ratings	Unit	
Collector to base voltage	V <sub>CBO</sub>	35	V	
Collector to emitter voltage	V <sub>CEO</sub>	35	V	
Emitter to base voltage	V <sub>EBO</sub>	4	V	
Collector current	Ι <sub>c</sub>	500	mA	
Collector power dissipation	Pc	300	mW	
Junction temperature	Тј	150	°C	
Storage temperature	Tstg	-55 to +150	°C	

#### **Electrical Characteristics** (Ta = 25°C)

Item	Symbol	Min	Тур	Max	Unit	Test conditions
Collector to base breakdown voltage	$V_{(\text{BR})\text{CBO}}$	35	_	_	V	$I_{c} = 10 \ \mu A, \ I_{E} = 0$
Collector to emitter breakdown voltage	$V_{(\text{BR})\text{CEO}}$	35	_	_	V	$I_c = 1 \text{ mA}, R_{BE} = \infty$
Emitter to base breakdown voltage	$V_{(BR)EBO}$	4	_	_	V	$I_{\rm E} = 10 \ \mu A, \ I_{\rm C} = 0$
Collector cutoff current	I <sub>CBO</sub>	—	—	0.5	μΑ	$V_{CB} = 20 \text{ V}, \text{ I}_{E} = 0$
DC current transfer ratio	$h_{FE1}^{*1}$	60		320		$V_{ce} = 3 \text{ V}, \text{ I}_{c} = 10 \text{ mA}$
	h <sub>FE2</sub>	10		_		$V_{ce} = 3 \text{ V}, \text{ I}_{c} = 500 \text{ mA}^{*2}$
Collector to emitter saturation voltage	$V_{\text{CE(sat)}}$	—	0.2	0.6	V	$I_{c} = 150 \text{ mA}, I_{B} = 15 \text{ mA}^{*2}$
Base to emitter voltage	V <sub>BE</sub>	_	0.64	_	V	$V_{ce} = 3 \text{ V}, \text{ I}_{c} = 10 \text{ mA}$
Notes: 1. The 2SC3553 is grouped by h <sub>FE1</sub> as follows.						
2. Pulse test						
B C D						

See characteristic curves of 2SC1213.

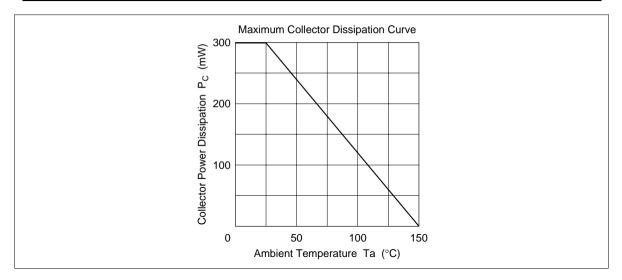
100 to 200

160 to 320

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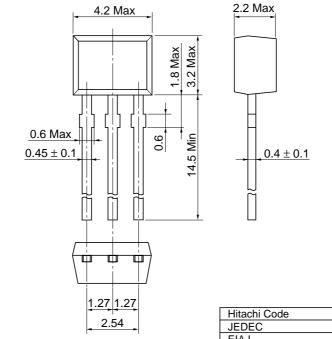
60 to 120

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Unit: mm



Hitachi Code	SPAK
JEDEC	_
EIAJ	—
Weight (reference value)	0.10 g

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